TRANSFER-PRINT SOLDER BALL MOUNTER BU-570

BGA rework equipment --- Solder ball placement system BU-570

(1) ■ Outside dimension: 84cm(L), 36cm(W), 59cm(H).
(2) ■ Weight: 42 kg.
(3) ■ Working voltage: AC-110V/50/60Hz / AC-/220V/50/60Hz
(4) ■ Working air pressure: 6 kg/cm².
(5) ■ Solder ball specification: According to the solder ball spec being used by different kinds of BGA package.
(6) ■ BGA IC holder: It is available for changing-over different types of BGA IC holders according to different size or spec of BGA package.
(7) ■ Solder ball screening fixture: It is available for changing-over different ball screening fixtures according to different size or spec of solder ball.
(8) ■ Solder ball placing speed: The speed for placing solder balls onto BGA pads can be adjusted and fine-tuning controlled.
(9) ■ Ball-placing yield rate: 98%.
(10) ■ Ball-placing accuracy: 0.03mm.
(11) ■ BGA IC holder unloading speed: Unloading speed；30~300 mm/s.
(12) ■ Automatic ball-placing operation cycle time : 42 seconds.

BGA regeneration!

~ Place solder balls on BGA to regenerate a whole new one with the lowest cost. ~

The solder ball placement system places new solder balls again onto ball removed BGA-IC for new reflowing rework. This equipment provides a technology promotion for traditional BGA operation in SMT industry. It is a very useful tool for BGA production.

[There are patents approved by lots of countries for this equipment. All rights are reserved]